

INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

Features

- Low $V_{CE(on)}$ Trench IGBT Technology
- Low Switching Losses
- 5 μ s SCSOA
- Square RBSOA
- 100% of The Parts Tested for I_{LM} ①
- Positive $V_{CE(on)}$ Temperature Coefficient.
- Ultra Fast Soft Recovery Co-pak Diode
- Tighter Distribution of Parameters
- Lead-Free, RoHS Compliant
- Automotive Qualified *

Benefits

- High Efficiency in a Wide Range of Applications
- Suitable for a Wide Range of Switching Frequencies due to Low $V_{CE(ON)}$ and Low Switching Losses
- Rugged Transient Performance for Increased Reliability
- Excellent Current Sharing in Parallel Operation
- Low EMI

Applications

- Air Conditioning Compressor

Ordering Information

Base part number	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRGB4062D1	TO-220	Tube	50	AUIRGB4062D1
AUIRGS4062D1	TO-262	Tube	50	AUIRGS4062D1
AUIRGS4062D1	D2Pak	Tube	50	AUIRGS4062D1
		Tape and Reel Left	800	AUIRGS4062D1TRL
		Tape and Reel Right	800	AUIRGS4062D1TRR

Absolute Maximum Ratings

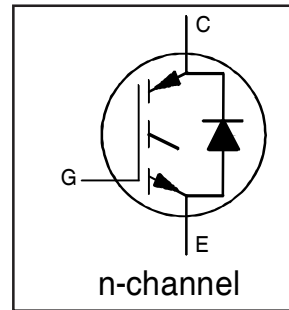
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ\text{C}$	Continuous Collector Current	59	A
$I_C @ T_C = 100^\circ\text{C}$	Continuous Collector Current	39	
$I_{NOMINAL}$	Nominal Current	24	
I_{CM}	Pulse Collector Current, $V_{GE} = 15\text{V}$	72	
I_{LM}	Clamped Inductive Load Current, $V_{GE} = 20\text{V}$ ①	96	
$I_F @ T_C = 25^\circ\text{C}$	Diode Continuous Forward Current	59	V
$I_F @ T_C = 100^\circ\text{C}$	Diode Continuous Forward Current	39	
I_{FM}	Diode Maximum Forward Current ②	96	
V_{GE}	Continuous Gate-to-Emitter Voltage	± 20	W
	Transient Gate-to-Emitter Voltage	± 30	
$P_D @ T_C = 25^\circ\text{C}$	Maximum Power Dissipation	246	°C
$P_D @ T_C = 100^\circ\text{C}$	Maximum Power Dissipation	123	
T_J	Operating Junction and	-55 to +175	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 sec. (1.6mm from case)	300	
	Mounting Torque, 6-32 or M3 Screw	10 lbf-in (1.1N·m)	

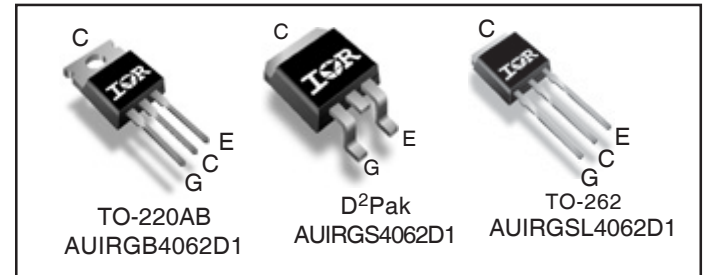
Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$ (IGBT)	Thermal Resistance Junction-to-Case (IGBT) ③	—	—	0.61	°C/W
$R_{\theta JC}$ (Diode)	Thermal Resistance Junction-to-Case (Diode) ③	—	—	1.2	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink (flat, greased surface)	—	0.50	—	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	—	62	—	

*Qualification standards can be found at <http://www.irf.com/>



$V_{CES} = 600\text{V}$
$I_{C(Nominal)} = 24\text{A}$
$t_{SC} \geq 5\mu\text{s}, T_{J(max)} = 175^\circ\text{C}$
$V_{CE(on)} \text{ typ.} = 1.57\text{V}$



G	C	E
Gate	Collector	Emitter

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	600	—	—	V	$V_{GE} = 0V, I_C = 100\mu A$ ③
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	0.3	—	V/ $^\circ\text{C}$	$V_{GE} = 0V, I_C = 10mA$ (25 $^\circ\text{C}$ -175 $^\circ\text{C}$)
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	1.57	1.77	V	$I_C = 24A, V_{GE} = 15V, T_J = 25^\circ\text{C}$
		—	1.87	—		$I_C = 24A, V_{GE} = 15V, T_J = 150^\circ\text{C}$
		—	1.94	—		$I_C = 24A, V_{GE} = 15V, T_J = 175^\circ\text{C}$
$V_{GE(th)}$	Gate Threshold Voltage	4.0	—	6.5	V	$V_{CE} = V_{GE}, I_C = 700\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Threshold Voltage temp. coefficient	—	-17	—	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 1.0mA$ (25 $^\circ\text{C}$ - 175 $^\circ\text{C}$)
g_{fe}	Forward Transconductance	—	12	—	S	$V_{CE} = 50V, I_C = 24A, PW = 20\mu s$
I_{CES}	Collector-to-Emitter Leakage Current	—	1.0	25	μA	$V_{GE} = 0V, V_{CE} = 600V$
		—	3.5	—	mA	$V_{GE} = 0V, V_{CE} = 600V, T_J = 175^\circ\text{C}$
V_{FM}	Diode Forward Voltage Drop	—	1.57	—	V	$I_F = 24A$
		—	1.40	—		$I_F = 19A$
		—	1.47	—		$I_F = 24A, T_J = 175^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 100	nA	$V_{GE} = \pm 20V$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	51	77	nC	$I_C = 24A$
Q_{ge}	Gate-to-Emitter Charge (turn-on)	—	14	21		$V_{GE} = 15V$
Q_{gc}	Gate-to-Collector Charge (turn-on)	—	21	32		$V_{CC} = 400V$
E_{on}	Turn-On Switching Loss	—	532	754	μJ	$I_C = 24A, V_{CC} = 400V, V_{GE} = 15V$
E_{off}	Turn-Off Switching Loss	—	311	526		$R_G = 10\Omega, L = 210\mu H, T_J = 25^\circ\text{C}$
E_{total}	Total Switching Loss	—	843	1280		Energy losses include tail & diode reverse recovery
$t_{d(on)}$	Turn-On delay time	—	19	36	ns	$I_C = 24A, V_{CC} = 400V, V_{GE} = 15V$
t_r	Rise time	—	24	41		$R_G = 10\Omega, L = 210\mu H, T_J = 25^\circ\text{C}$
$t_{d(off)}$	Turn-Off delay time	—	90	109		
t_f	Fall time	—	23	40		
E_{on}	Turn-On Switching Loss	—	726	—	μJ	$I_C = 24A, V_{CC} = 400V, V_{GE} = 15V$
E_{off}	Turn-Off Switching Loss	—	549	—		$R_G = 10\Omega, L = 210\mu H, T_J = 175^\circ\text{C}$ ③
E_{total}	Total Switching Loss	—	1275	—		Energy losses include tail & diode reverse recovery
$t_{d(on)}$	Turn-On delay time	—	12	—	ns	$I_C = 24A, V_{CC} = 400V, V_{GE} = 15V$
t_r	Rise time	—	23	—		$R_G = 10\Omega, L = 200\mu H, L_S = 150nH$
$t_{d(off)}$	Turn-Off delay time	—	92	—		$T_J = 175^\circ\text{C}$
t_f	Fall time	—	84	—		
C_{ies}	Input Capacitance	—	1487	—	pF	$V_{GE} = 0V$
C_{oes}	Output Capacitance	—	118	—		$V_{CC} = 30V$
C_{res}	Reverse Transfer Capacitance	—	44	—		$f = 1.0MHz$
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				$T_J = 175^\circ\text{C}, I_C = 96A$ $V_{CC} = 480V, V_p \leq 600V$ $R_G = 10\Omega, V_{GE} = +20V$ to 0V
SCSOA	Short Circuit Safe Operating Area	5	—	—	μs	$V_{CC} = 400V, V_p \leq 600V$ $R_G = 10\Omega, V_{GE} = +15V$ to 0V
E_{rec}	Reverse Recovery Energy of the Diode	—	773	—	μJ	$T_J = 175^\circ\text{C}$
t_{rr}	Diode Reverse Recovery Time	—	102	—	ns	$V_{CC} = 400V, I_F = 24A$
I_{rr}	Peak Reverse Recovery Current	—	32	—	A	$V_{GE} = 15V, R_G = 10\Omega, L = 210\mu H$

Notes:

- ① $V_{CC} = 80\% (V_{CES}), V_{GE} = 20V, L = 210\mu H, R_G = 50\Omega$.
- ② Pulse width limited by max. junction temperature.
- ③ R_G is measured at T_J of approximately 90 $^\circ\text{C}$.
- ④ Maximum limits are based on statistical sample size characterization.

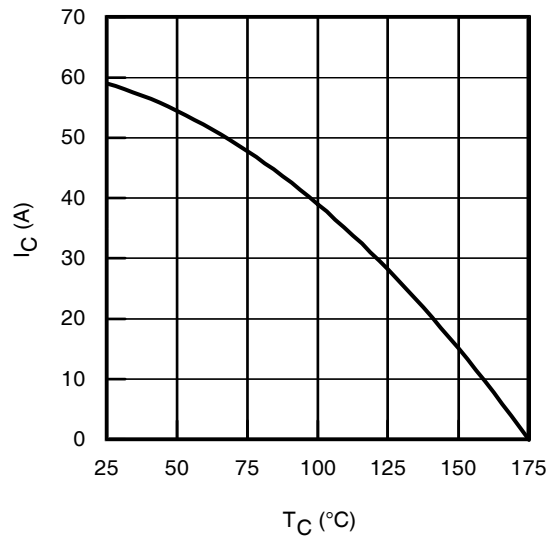


Fig. 1 - Maximum DC Collector Current vs. Case Temperature

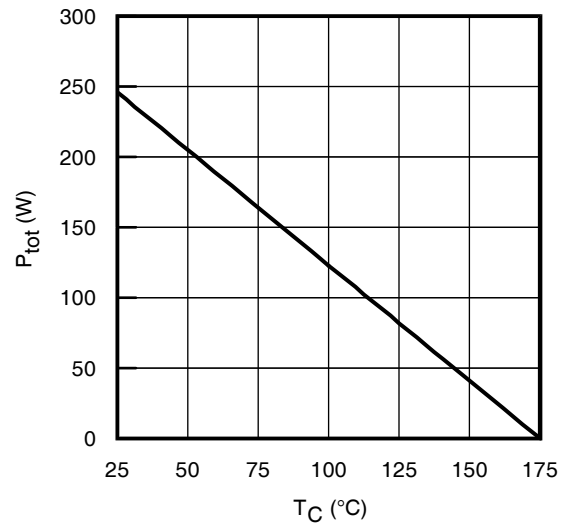


Fig. 2 - Power Dissipation vs. Case Temperature

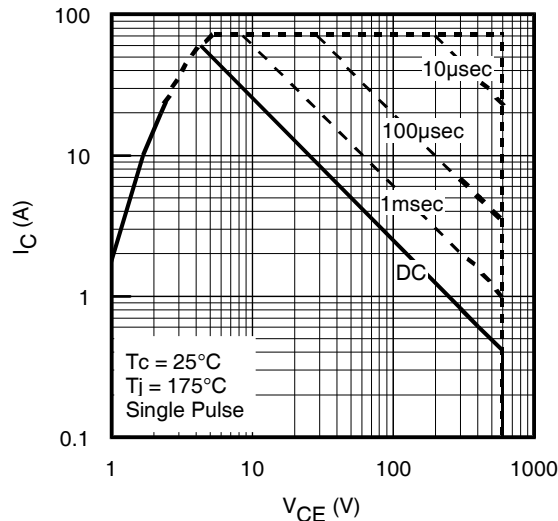


Fig. 3 - Forward SOA
 $T_C = 25^\circ\text{C}$, $T_J \leq 175^\circ\text{C}$; $V_{GE} = 15\text{V}$

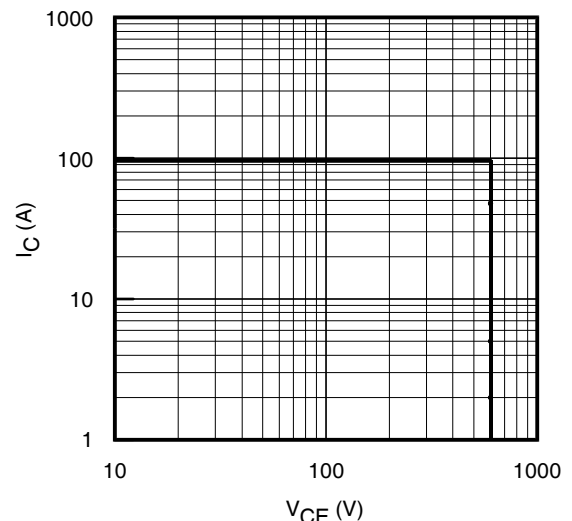


Fig. 4 - Reverse Bias SOA
 $T_J = 175^\circ\text{C}$; $V_{GE} = 20\text{V}$

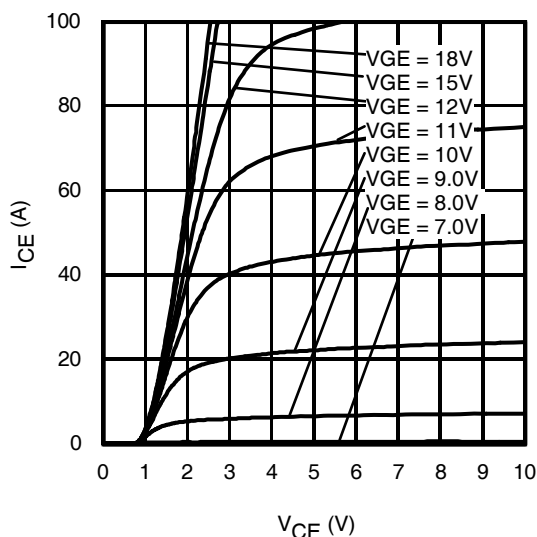


Fig. 5 - Typ. IGBT Output Characteristics
 $T_J = -40^\circ\text{C}$; $t_p = 20\mu\text{s}$

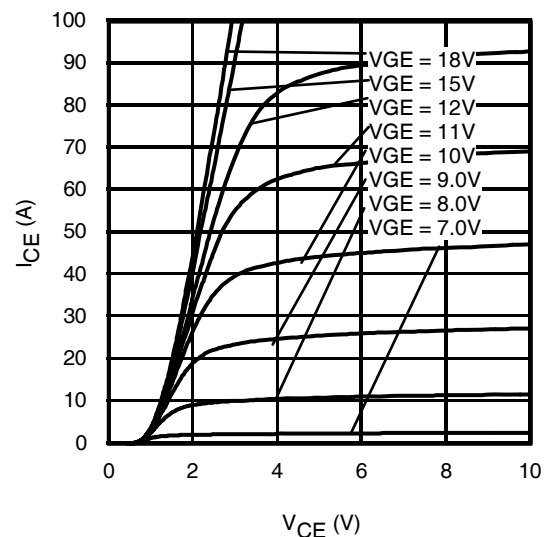


Fig. 6 - Typ. IGBT Output Characteristics
 $T_J = 25^\circ\text{C}$; $t_p = 20\mu\text{s}$

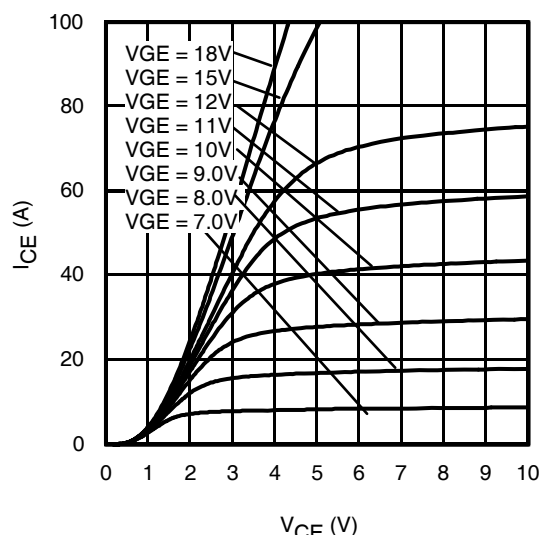


Fig. 7 - Typ. IGBT Output Characteristics
 $T_J = 175^\circ\text{C}$; $t_p = 20\mu\text{s}$

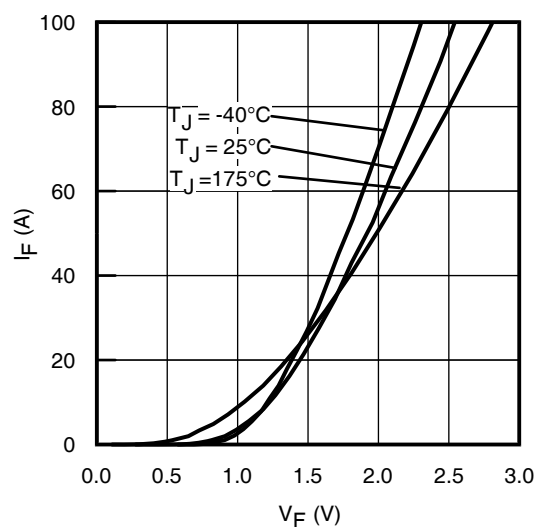


Fig. 8 - Typ. Diode Forward Characteristics
 $t_p = 20\mu\text{s}$

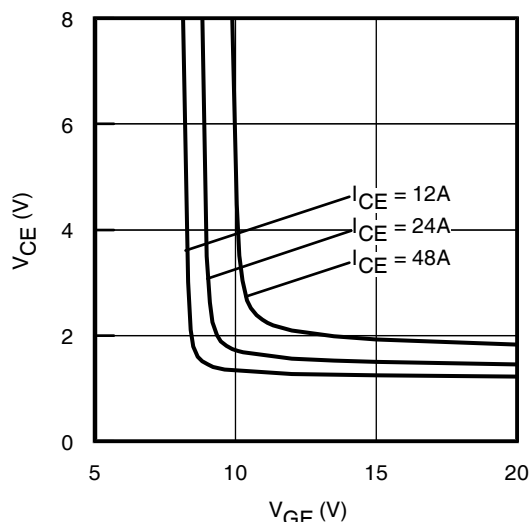


Fig. 9 - Typical V_{CE} vs. V_{GE}
 $T_J = -40^\circ\text{C}$

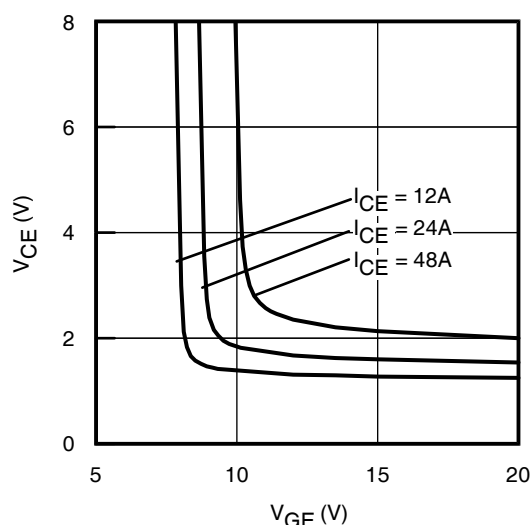


Fig. 10 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

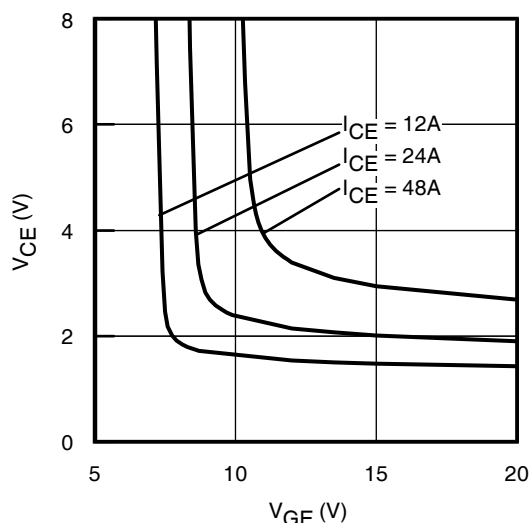


Fig. 11 - Typical V_{CE} vs. V_{GE}
 $T_J = 175^\circ\text{C}$

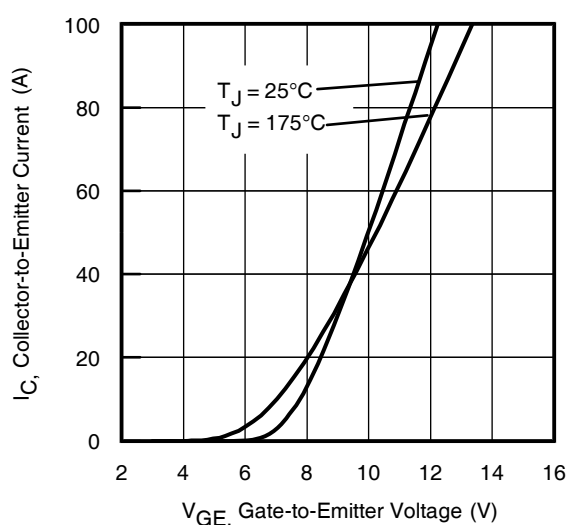
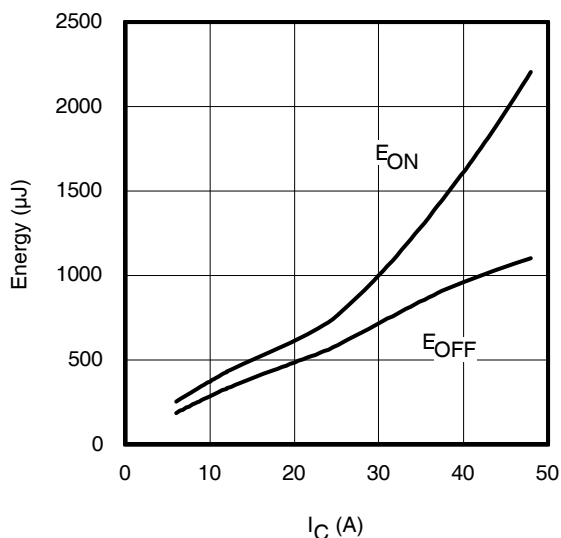
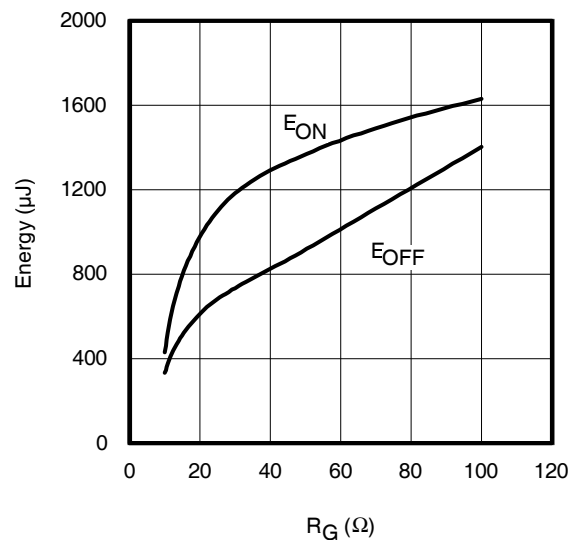
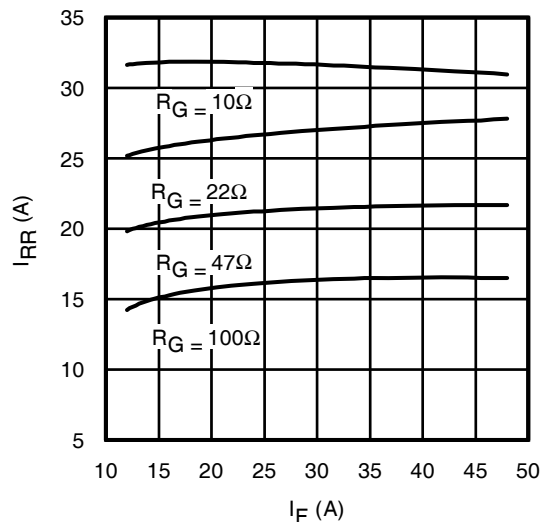
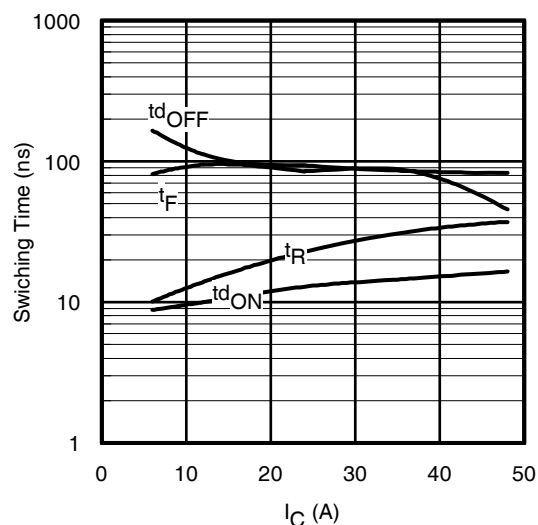
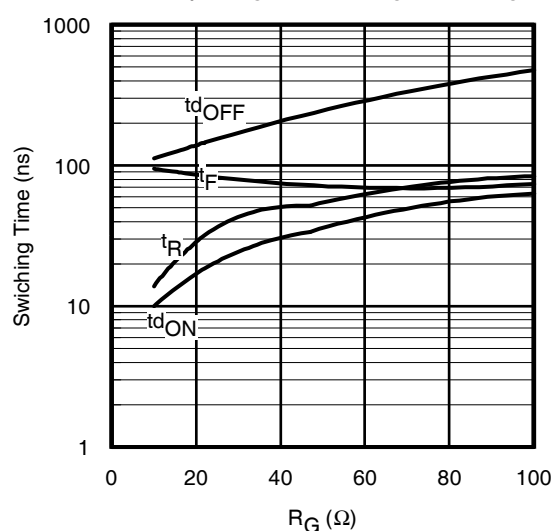
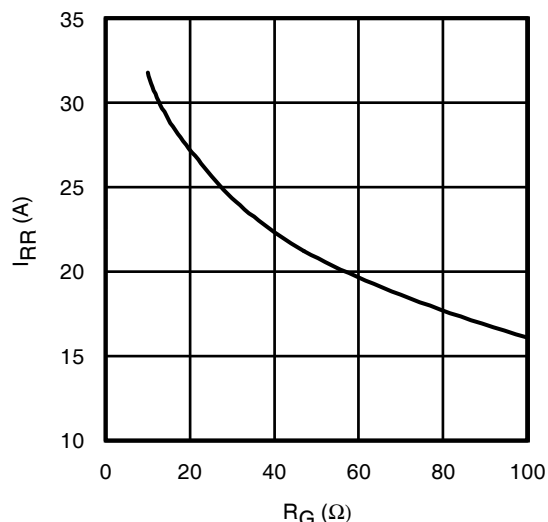


Fig. 12 - Typ. Transfer Characteristics
 $V_{CE} = 50\text{V}$; $t_p = 20\mu\text{s}$


Fig. 13 - Typ. Energy Loss vs. I_C
 $T_J = 175^\circ\text{C}; L = 210\mu\text{H}; V_{CE} = 400\text{V}; R_G = 10\Omega; V_{GE} = 15\text{V}$

Fig. 15 - Typ. Energy Loss vs. R_G
 $T_J = 175^\circ\text{C}; L = 210\mu\text{H}; V_{CE} = 400\text{V}; I_{CE} = 24\text{A}; V_{GE} = 15\text{V}$

Fig. 17 - Typ. Diode I_{RR} vs. I_F
 $T_J = 175^\circ\text{C}$

Fig. 14 - Typ. Switching Time vs. I_C
 $T_J = 175^\circ\text{C}; L = 210\mu\text{H}; V_{CE} = 400\text{V}; R_G = 10\Omega; V_{GE} = 15\text{V}$

Fig. 16 - Typ. Switching Time vs. R_G
 $T_J = 175^\circ\text{C}; L = 210\mu\text{H}; V_{CE} = 400\text{V}; I_{CE} = 24\text{A}; V_{GE} = 15\text{V}$

Fig. 18 - Typ. Diode I_{RR} vs. R_G
 $T_J = 175^\circ\text{C}$

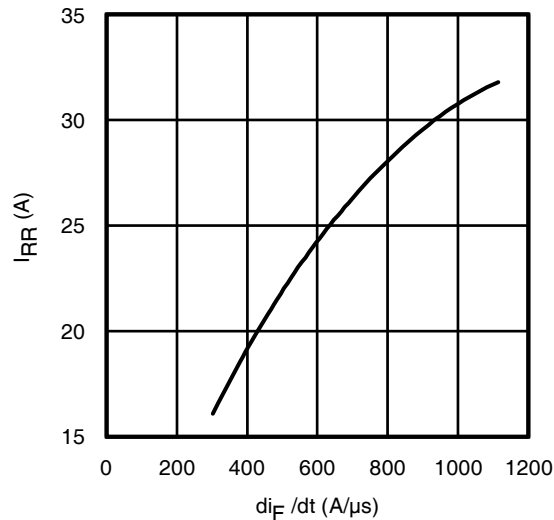


Fig. 19 - Typ. Diode I_{RR} vs. di_F/dt
 $V_{CC} = 400V$; $V_{GE} = 15V$; $I_F = 24A$; $T_J = 175^\circ C$

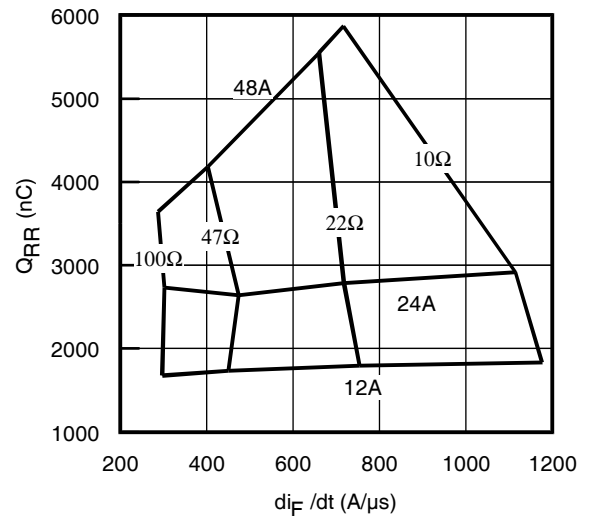


Fig. 20 - Typ. Diode Q_{RR} vs. di_F/dt
 $V_{CC} = 400V$; $V_{GE} = 15V$; $T_J = 175^\circ C$

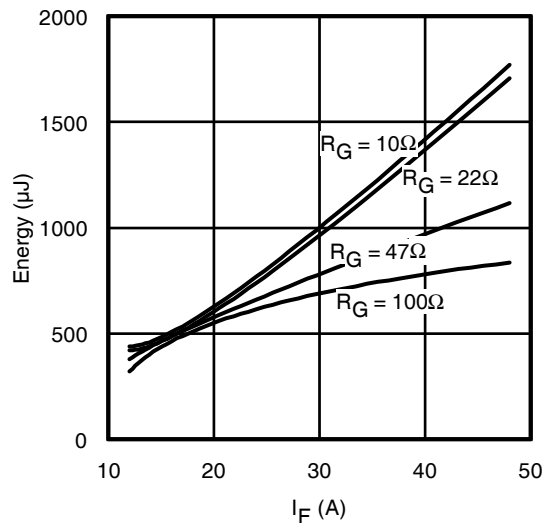


Fig. 21 - Typ. Diode E_{RR} vs. I_F
 $T_J = 175^\circ C$

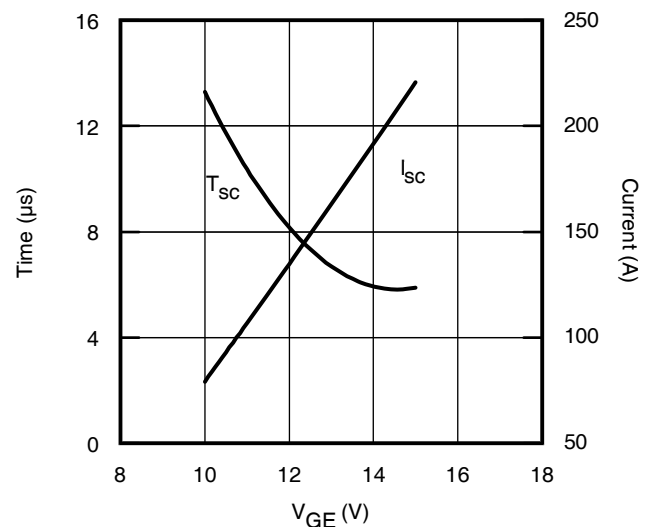


Fig. 22 - V_{GE} vs. Short Circuit Time
 $V_{CC} = 400V$; $T_C = 25^\circ C$

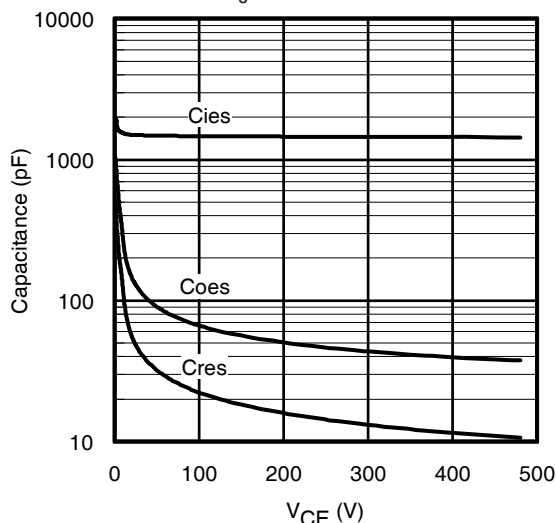


Fig. 23 - Typ. Capacitance vs. V_{CE}
 $V_{GE} = 0V$; $f = 1MHz$

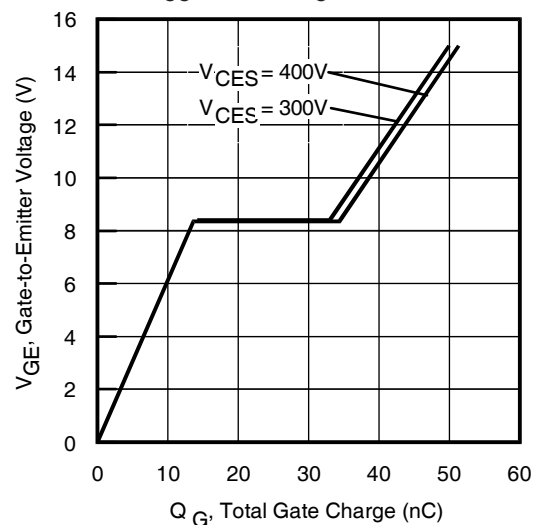


Fig. 24 - Typical Gate Charge vs. V_{GE}
 $I_{CE} = 24A$; $L = 585\mu H$

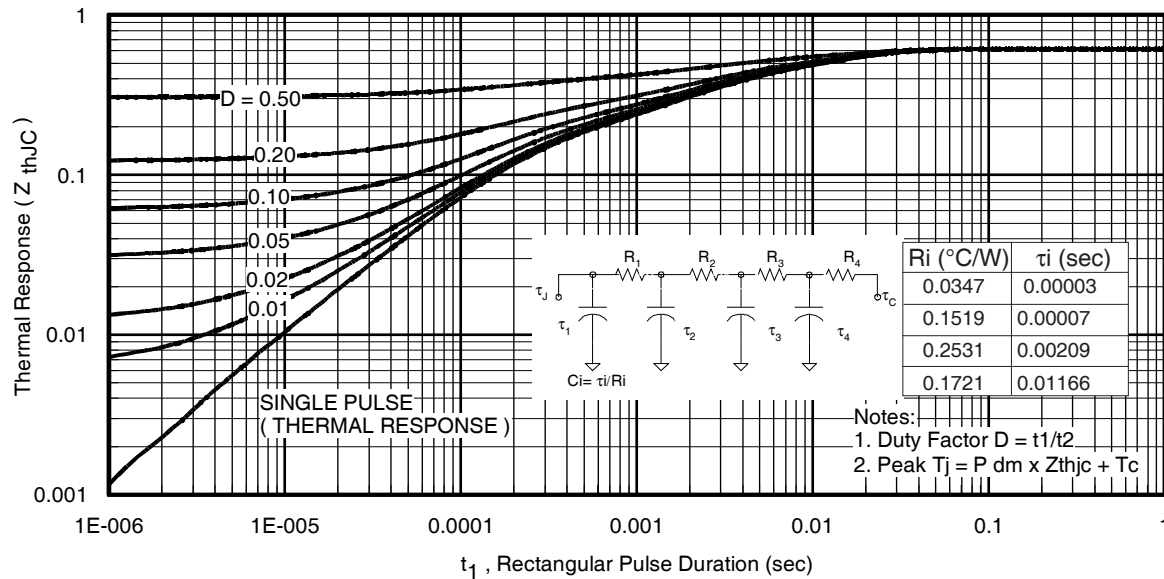


Fig 25. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

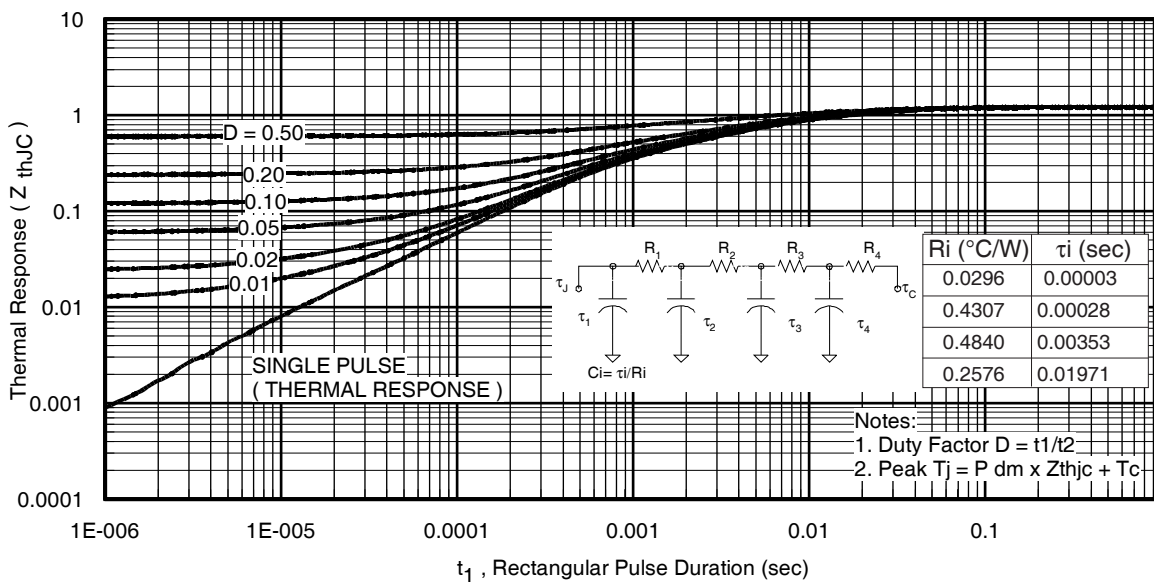


Fig. 26. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

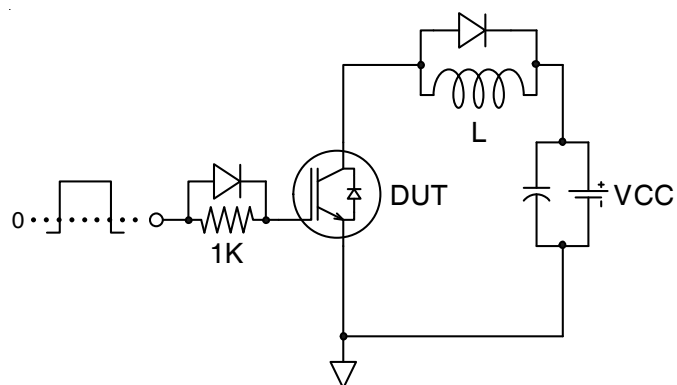


Fig.C.T.1 - Gate Charge Circuit (turn-off)

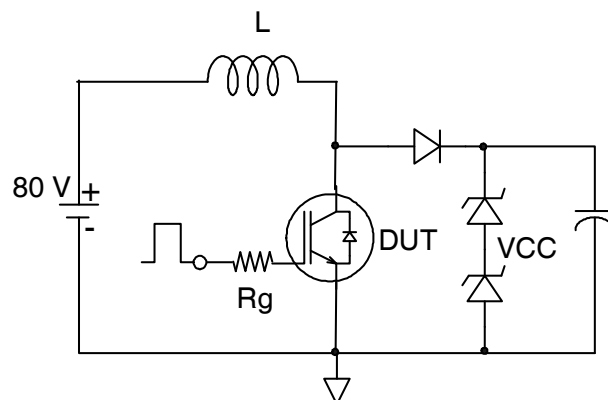


Fig.C.T.2 - RBSOA Circuit

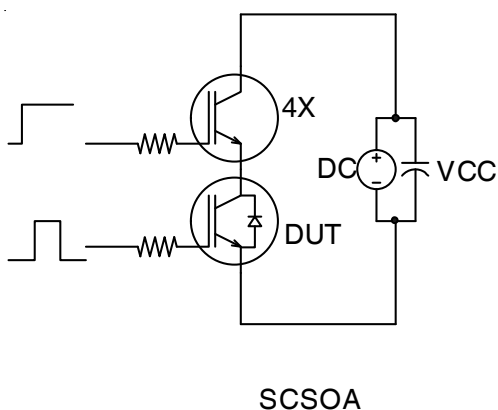


Fig.C.T.3 - S.C. SOA Circuit

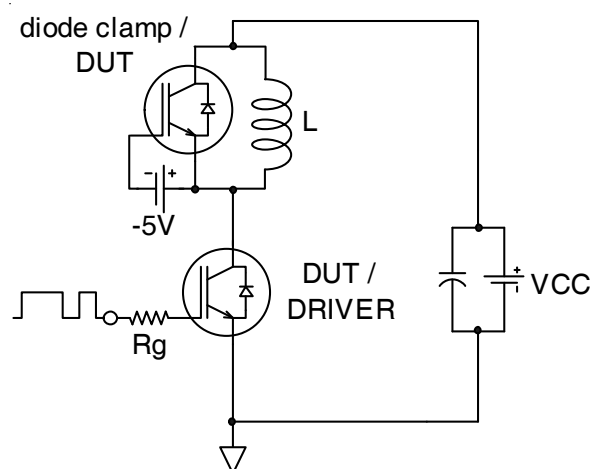


Fig.C.T.4 - Switching Loss Circuit

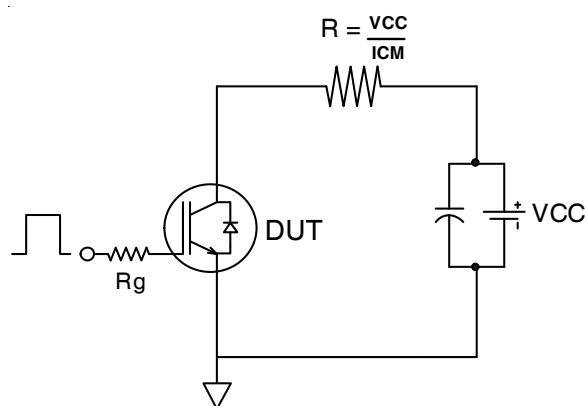


Fig.C.T.5 - Resistive Load Circuit

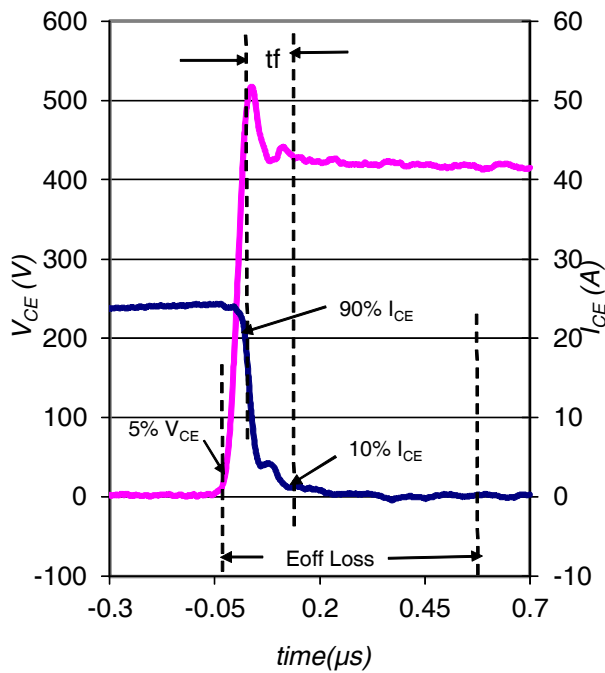


Fig. WF1 - Typ. Turn-off Loss Waveform
@ $T_J = 175^\circ\text{C}$ using Fig. CT.4

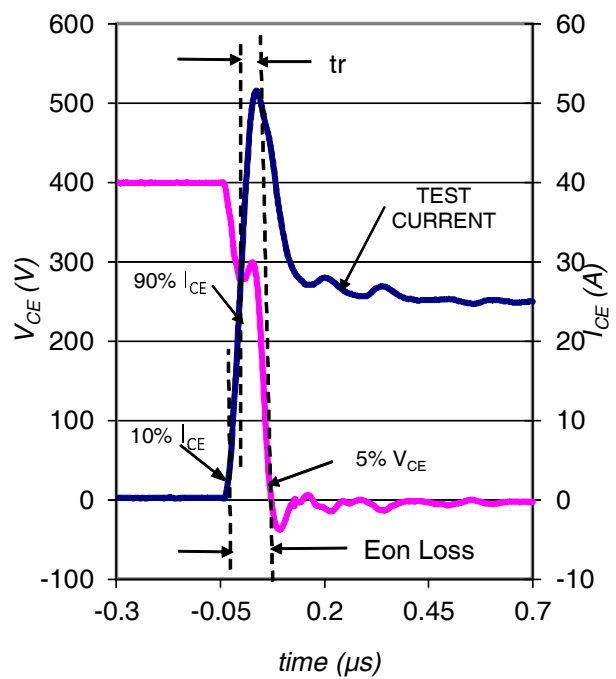


Fig. WF2 - Typ. Turn-on Loss Waveform
@ $T_J = 175^\circ\text{C}$ using Fig. CT.4

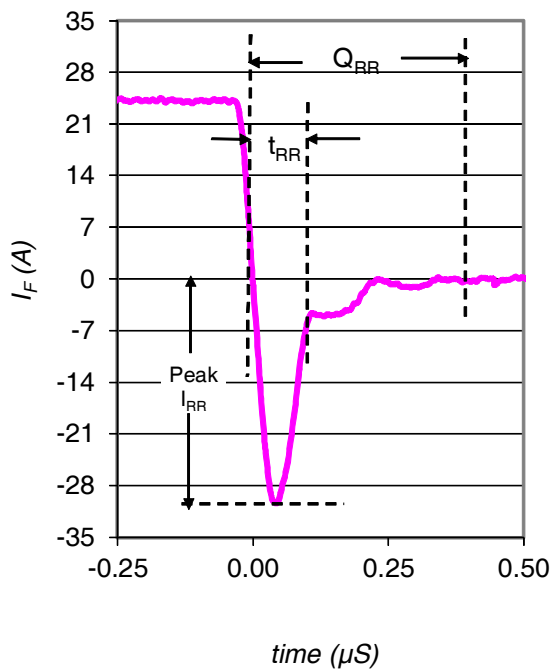


Fig. WF3 - Typ. Diode Recovery Waveform
@ $T_J = 175^\circ\text{C}$ using Fig. CT.4

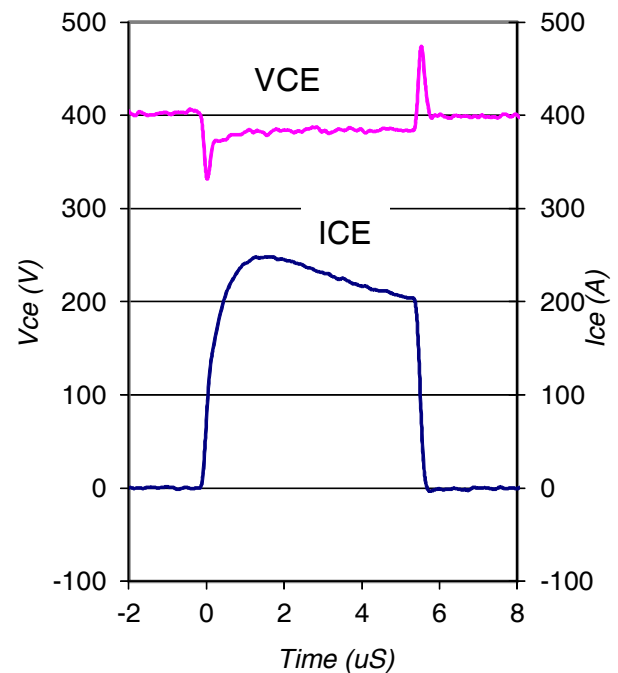
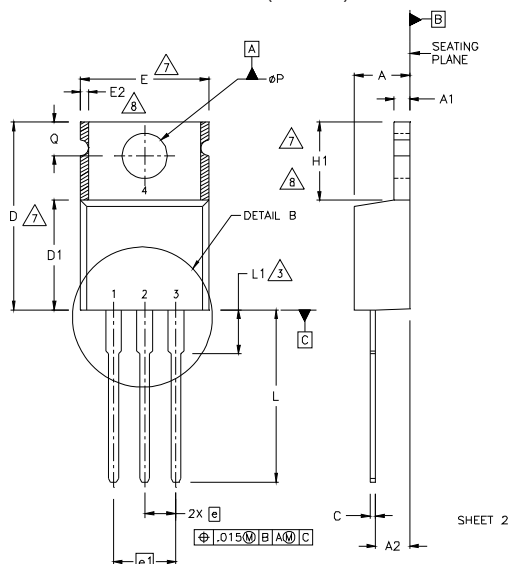


Fig. WF4 - Typ. S.C. Waveform
@ $T_J = 25^\circ\text{C}$ using Fig. CT.3

TO-220AB Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
2. DIMENSIONS ARE SHOWN IN INCHES (MILLIMETERS).
3. LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. DIMENSION b1 & c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION : INCHES.
7. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
8. DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.

LEAD ASSIGNMENTS

HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE

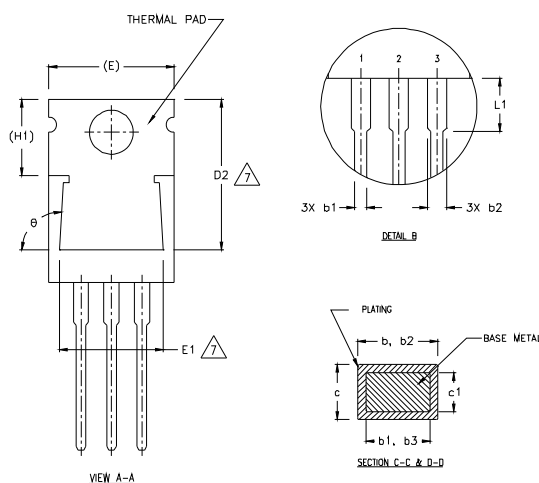
IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER

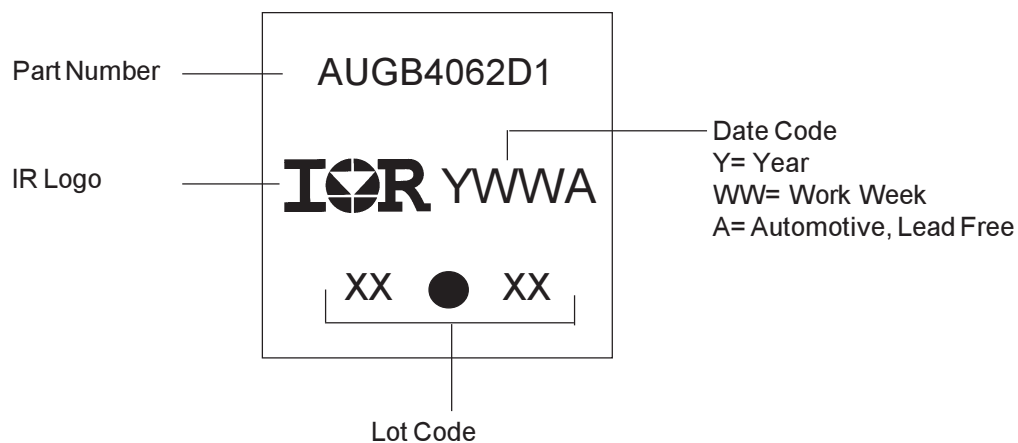
DIODES

- 1.- ANODE/OPEN
- 2.- CATHODE
- 3.- ANODE

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	3.56	4.82	.140	.190	5
A1	0.51	1.40	.020	.055	
A2	2.04	2.92	.080	.115	
b	0.38	1.01	.015	.040	
b1	0.38	0.96	.015	.038	
b2	1.15	1.77	.045	.070	5
b3	1.15	1.73	.045	.068	
c	0.36	0.61	.014	.024	
c1	0.36	0.56	.014	.022	
D	14.22	16.51	.560	.650	4
D1	8.38	9.02	.330	.355	7
D2	12.19	12.88	.480	.507	
E	9.66	10.66	.380	.420	
E1	8.38	8.89	.330	.350	
e	2.54 BSC		.100 BSC		7,8
e1	5.08		.200 BSC		
H1	5.85	6.55	.230	.270	
L	12.70	14.73	.500	.580	
L1	—	6.35	—	.250	3
øP	3.54	4.08	.139	.161	3
Q	2.54	3.42	.100	.135	
ø	90°-93°		90°-93°		



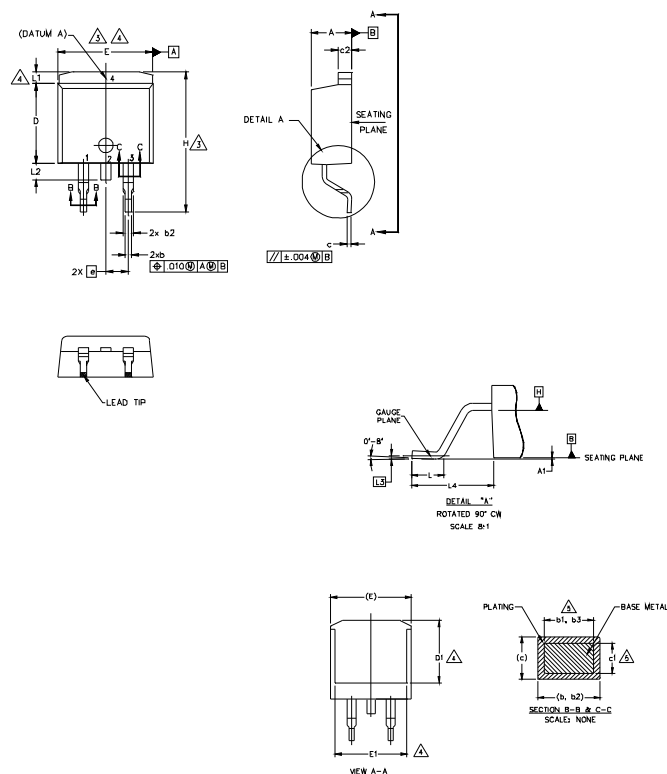
TO-220AB Part Marking Information



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

D²Pak (TO-263AB) Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [0.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
7. CONTROLLING DIMENSION: INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-263AB.

SYMBOL	DIMENSIONS				NOTES	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	4.06	4.83	.160	.190	5	
A1	0.00	0.254	.000	.010		
b	0.51	0.99	.020	.039		
b1	0.51	0.89	.020	.035		
b2	1.14	1.78	.045	.070		
b3	1.14	1.73	.045	.068	5	
c	0.38	0.74	.015	.029	5	
c1	0.38	0.58	.015	.023		
c2	1.14	1.65	.045	.065		
D	8.38	9.65	.330	.380		3
D1	6.86	—	.270	—		4
E	9.65	10.67	.380	.420	3,4	
E1	6.22	—	.245	—	4	
e	2.54 BSC		.100 BSC		4	
H	14.61	15.88	.575	.625		
L	1.78	2.79	.070	.110		
L1	—	1.65	—	.066		
L2	1.27	1.78	—	.070		
L3	0.25 BSC		.010 BSC			
L4	4.78	5.28	.188	.208		

LEAD ASSIGNMENTS

HEXFET

- 1.— GATE
- 2, 4.— DRAIN
- 3.— SOURCE

IGBTs, CoPACK

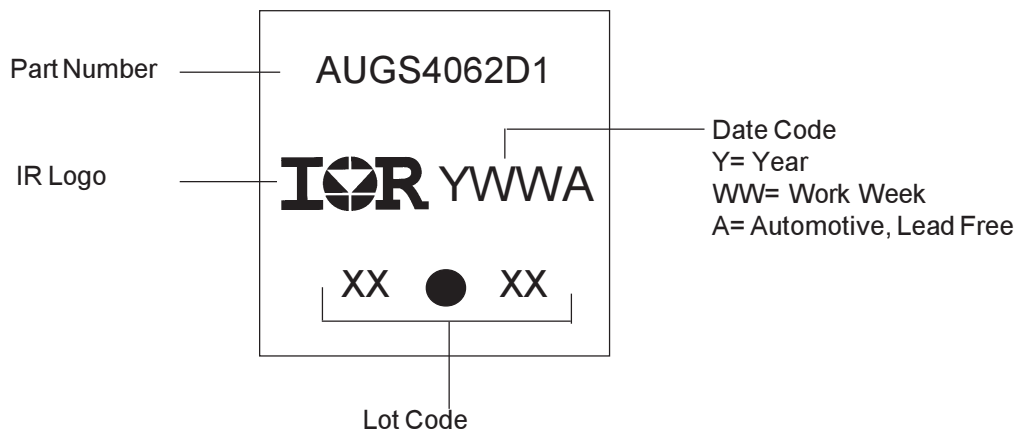
- 1.— GATE
- 2, 4.— COLLECTOR
- 3.— EMITTER

DIODES

- 1.— ANODE *
- 2, 4.— CATHODE
- 3.— ANODE

* PART DEPENDENT.

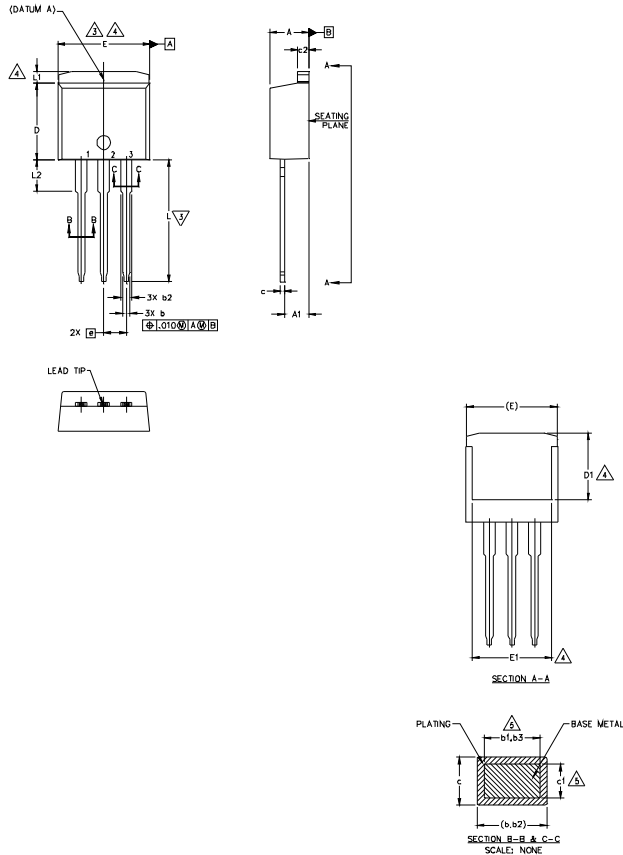
D²Pak (TO-263AB) Part Marking Information



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

TO-262 Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [0.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION: INCH.
7. OUTLINE CONFORM TO JEDEC TO-262 EXCEPT A1(max.), b(min.) AND D1(min.) WHERE DIMENSIONS DERIVED THE ACTUAL PACKAGE OUTLINE.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	2.03	3.02	.080	.119	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	5
b2	1.14	1.78	.045	.070	
b3	1.14	1.73	.045	.068	5
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	5
c2	1.14	1.65	.045	.065	
D	8.38	9.65	.330	.380	3
D1	6.86	—	.270	—	4
E	9.65	10.67	.380	.420	3,4
E1	6.22	—	.245	—	4
e	2.54 BSC		.100 BSC		
L	13.46	14.10	.530	.555	
L1	—	1.65	—	.065	4
L2	3.56	3.71	.140	.146	

LEAD ASSIGNMENTS

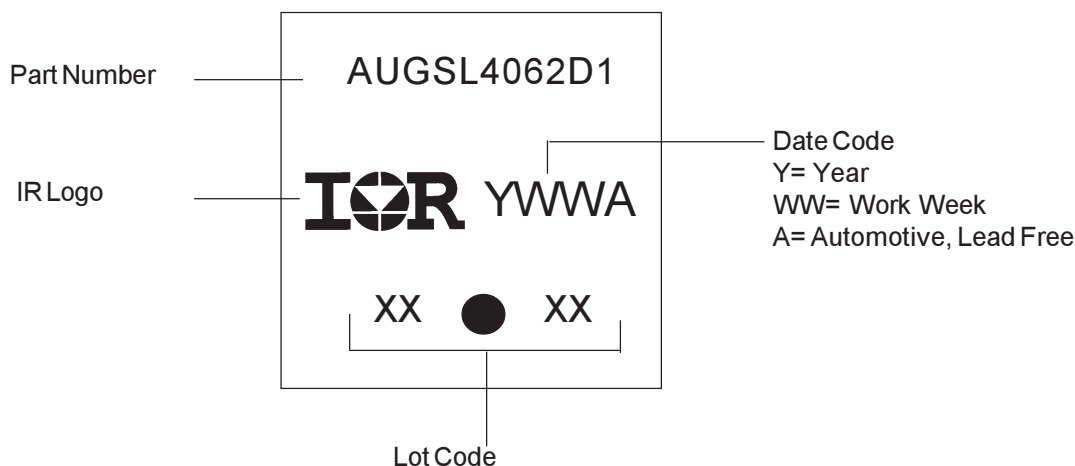
HEXFET

1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

IGBTs, CoPACK

1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

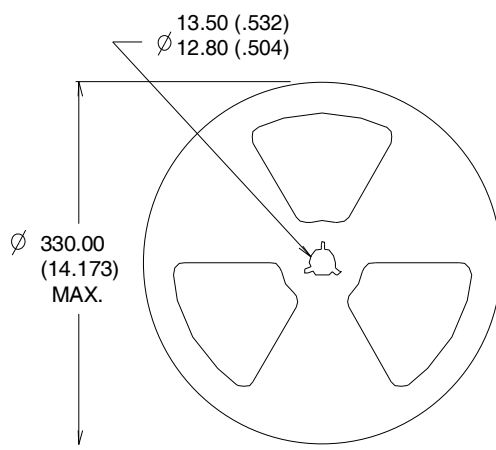
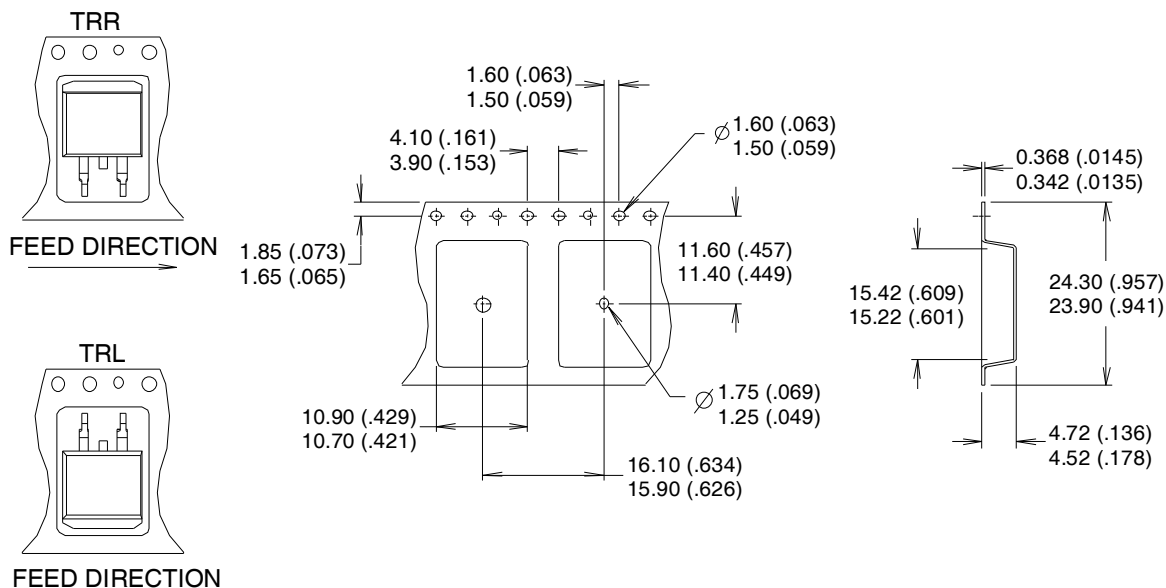
TO-262 Part Marking Information



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

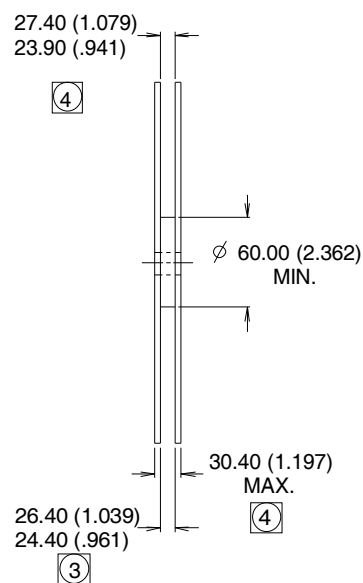
D²Pak Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :

1. COMFORMS TO EIA-418.
2. CONTROLLING DIMENSION: MILLIMETER.
- ③ DIMENSION MEASURED @ HUB.
- ④ INCLUDES FLANGE DISTORTION @ OUTER EDGE.



Qualification Information[†]

Qualification Level		Automotive (per AEC-Q101) ^{††}	
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		3L-TO-220	N/A
		3L-TO-262	
		3L-D2 PAK	MSL1
ESD	Machine Model	Class M4 (+/- 700V) (per AEC-Q101-002)	
	Human Body Model	Class H1C (+/- 2000V) (per AEC-Q101-001)	
	Charged Device Model	Class C5 (+/- 2000V) (per AEC-Q101-005)	
RoHS Compliant		Yes	

[†] Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/>

^{††} Highest passing voltage.

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For technical support, please contact IR’s Technical Assistance Center

<http://www.irf.com/technical-info/>

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